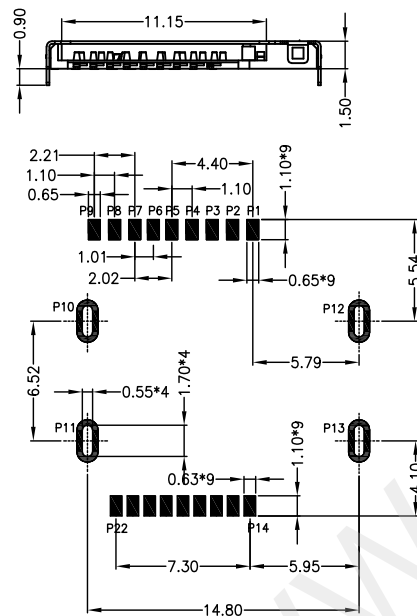
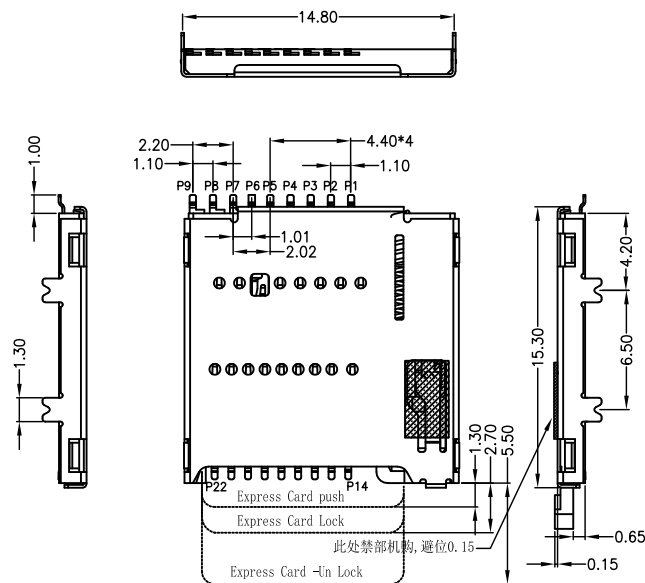
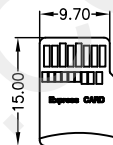
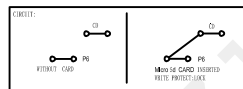
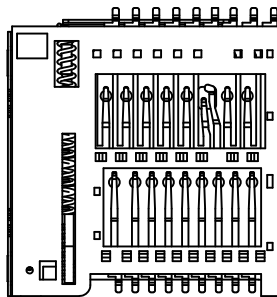
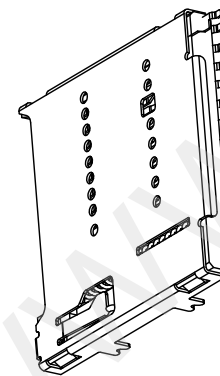




RECOMMEND PCB LAYOUT:  PCB AREA 焊接区
(Unit:mm .X $\pm$ 0.15 .XX $\pm$ 0.05 .XXX $\pm$ 0.02)



PIN NO.	MICRO SD EXPRESS CARD
P1	DAT2 信号
P2	CD/DAT3 信号
P3	CMD 数据输入
P4	VDD1 电压/电源
P5	CLK 时钟
P6	Vss 接地
P7	DAT0/RCLK+
P8	DAT1/RCLK-
P9	检测P
P10	GND
P11	GND
P12	GND
P13	GND
P14	MICRO SD Vdd2
P15	MICRO SD VDD3
P16	MICRO SD Vss
P17	MICRO SD PCLE TX+
P18	MICRO SD PCLE TX-
P19	MICRO SD Vss
P20	MICRO SD PCLE RX+
P21	MICRO SD PCLE RX-
P22	MICRO SD Vss



MATERIAL:

Specification

Insulator: High Temperature Thermoplastic,
UL 94V-0. COLOR*BLACK LCP

(塑胶: 黑色LCP, 防火等级UL 94V-0)

SHELL: SUS301

Contact: Copper Alloy (磷铜C5210)

弹簧: 琴钢线

拉杆: SUS301

PLATING:

Contact: All Ni50u, contact area 1u Au, Pad 0.8u Au

(接触端子电镀: 全部镍底50u, 接触区域1u金, 焊脚处0.8u金最少)

Shell: All 50u Ni, Pad 0.8u Au

(外壳电镀: 镍底50u, 焊脚处0.8u金)

Electrical:

Current Rating :0.5Amps max(额定电流:0.5A最大)

Voltage Rating :5V AC/DC(额定电压:5V AC/DC)

Ambient Temperature Range : -20° C~+60° C(工作温度: -20度到+60度)

Storage Temperature Range : -40° C~+70° C(工作环境: -20度到+80度)

Ambient Humidity Range :95% R.H. Max. (上锡效果: 95%以上)

Contact Resistance:100m Ω max. (端子接触电阻: 100m Ω 最大)

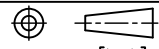
Insulation Resistance:1000 Ω min./500VDC(绝缘阻抗: 100兆欧最小)

Mating Cycles:3,000 Insertions (寿命: 3000次)

产品耐温温度: 260° C



深圳市华宇创精密电子有限公司

TOLERANCE: X.X $\pm$ 0.30 X.XX $\pm$ 0.25 X.XXX $\pm$ 0.15 X' $\pm$ 2" X.X" $\pm$ 0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF PUSH 7.1卡座 DIP脚 1.5H
 UNIT: mm [inch]	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC135-TF18-150
SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2202191344
			SHEET NO. 1 OF 1